

HD MEZZ ELEVATED ARRAY HDAM SERIES

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HDAM

- Insulator Material:** Black Liquid Crystal Polymer
- Contact Material:** Copper Alloy
- Current Rating:** 2.3A @ 80°C ambient
- Operating Temp Range:** -55°C to +125°C
- Plating:** Au or Sn over 50µ" (1,27µm) Ni
- Contact Resistance:** 19 mΩ max
- Working Voltage:** 200 VAC
- Mated Cycles:** 100
- RoHS Compliant:** Yes

Processing:

- Max Processing Temp:** 230°C for 60 seconds, or 260°C for 20 seconds 3x
- Lead-Free Solderable:** Yes

Mates with: HDAF



MATED HEIGHTS*		
HDAM LEAD STYLE	HDAF LEAD STYLE	
	-08.0	-18.0
-12.0	20mm	30mm
-17.0	25mm	35mm

*Processing conditions will affect mated height.

Intermateable with Molex HD Mezz

299, 195 and 143 pins

Elevated stack heights of 20mm, 25mm, 30mm and 35mm

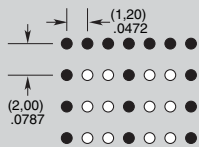
Open pin field for Single-Ended or Differential Pair configurations

Choice of Tin-Lead or Lead-Free Solder Charge

35mm Stack Height	Rated @ -3dB Insertion Loss*
Single-Ended Signaling	9.0 GHz / 18.0 Gbps
Differential Pair Signaling	9.0 GHz / 18.0 Gbps

*Data based on simulations using Final Inch® design.

DIFFERENTIAL APPLICATIONS



ARRAY	PAIR COUNT*
11x13	44
15x13	60
23x13	92

*2:1 S:G Ratio

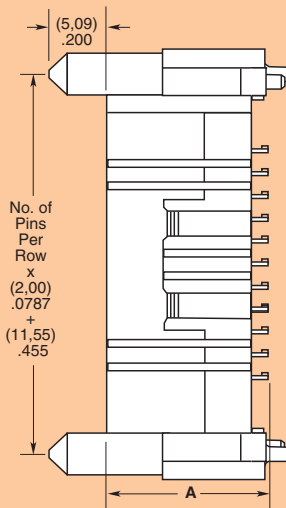
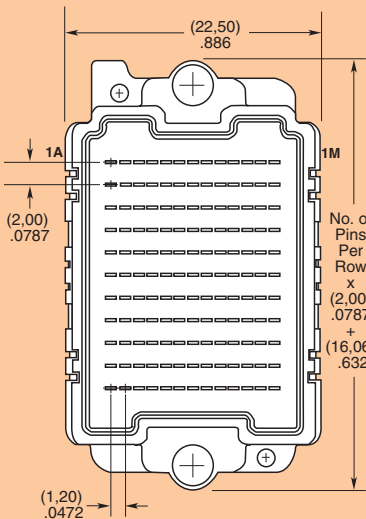
ALSO AVAILABLE

Tin-Lead Solder Charge. Call Samtec.

Note: HD Mezz is a trademark of Molex Incorporated

Note: Some lengths, styles and options are non-standard, non-returnable.

HDAM	NO. OF PINS PER ROW	LEAD STYLE	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	OTHER OPTION
	-11, -15, -23	Specify LEAD STYLE from chart	-S = 30µ" (0,76µm) Gold on contact area, Matte Tin on tails and guide pins	-13	-2 = Lead-Free Tin Alloy 95.5% Sn/ 3.8% Ag/0.7% Cu Solder Charge	-P = Pick & Place Pad



LEAD STYLE	A
-12.0	(14,41) .567
-17.0	(19,41) .764

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM